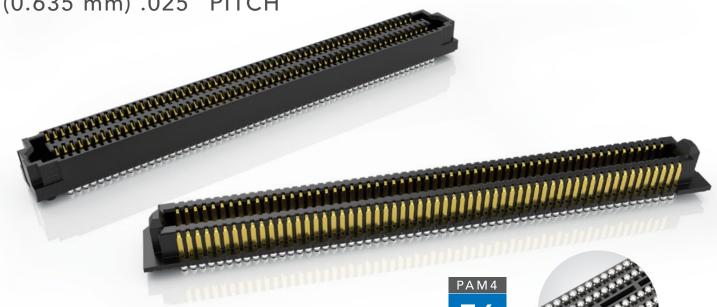
ACCELERATE®HD

HIGH-DENSITY SLIM BODY ARRAYS

(0.635 mm) .025" PITCH



FEATURES & BENEFITS

- Up to 400 positions in 4-row design
- 5 mm, 7 mm, 9 mm, 10 mm, 11 mm, 12 mm 14 mm & 16 mm stack heights
- Slim 5 mm width body design
- Edge Rate® contact system optimized for signal integrity performance
- Open-pin-field for grounding and routing flexibility
- PCIe® 5.0 capable
- Compatible with mPower® (UMPT/UMPS) for a power signal solution

HIGHER DENSITY THAN PREVIOUS GENERATION STRIPS

Solder ball technology

for simplified processing

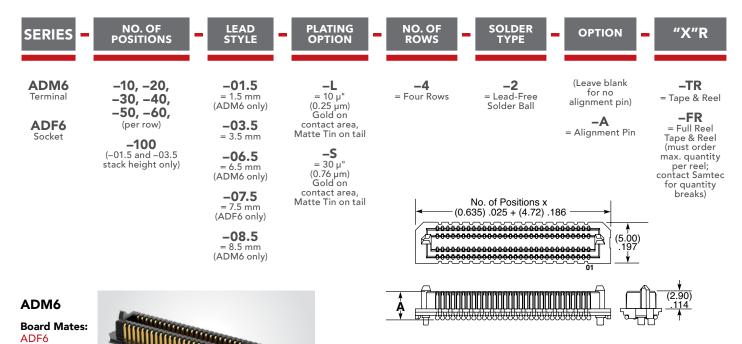
ADM6/ADF6 Series (400 total positions)

KEY SPECIFICATIONS

PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
(0.635 mm) .025"	40 - 400	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.34 A per pin (4 pins powered)	Testing now	Yes



(0.635 mm) .025" PITCH • SLIM BODY OPEN-PIN-FIELD ARRAYS



LEAD STYLE	A
-01.5	(3.40) .134
-03.5	(5.40) .213
-06.5	(8.40) .331
-08.5	(10.40) .409

View complete specifications at: samtec.com?ADM6

MATED HEIGHTS *						
ADF6	ADM6 LEAD STYLE					
LEAD STYLE	-01.5	-03.5	-06.5	-08.5		
-03.5	(5 mm) .197"	(7 mm) .276"	(10 mm) .394"	(12 mm) .472"		
-07.5	(9 mm) .354"	(11 mm) .433"	(14 mm) .551"	(16 mm) .630"		
* Processing cor	Processing conditions will affect mated height					

ADF6

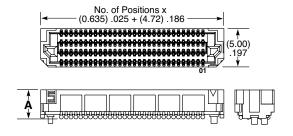
Standoffs: JSO

Board Mates: ADM6

Standoffs:



LEAD STYLE	A
-03.5	(3.73) .147
-07.5	(7.73)



Notes:

Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?ADF6